

## 40V N And P-Channel Enhancement Mode MOSFET

**Description**

The PECN4614D6 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

**General Features**

## ◆ N-channel:

$V_{DS} = 40V, ID = 16A$

$R_{DS(ON)} = 15m\Omega$  (typical) @  $VGS = 10V$

$R_{DS(ON)} = 17m\Omega$  (typical) @  $VGS = 4.5V$

## P-Channel:

$V_{DS} = -40V, ID = -16A$

$R_{DS(ON)} = 29m\Omega$  (typical) @  $VGS = -10V$

$R_{DS(ON)} = 38.5m\Omega$  (typical) @  $VGS = -4.5V$

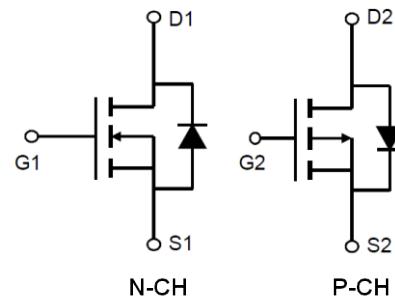
- ◆ Excellent gate charge  $\times R_{DS(ON)}$  product(FOM)
- ◆ Very low on-resistance  $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

**Application**

*100% UIS TESTED!*

*100%  $\Delta Vds$  TESTED!*

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

**Schematic diagram****Marking and pin assignment**

PDFN5×6-8L-B



Top View



Bottom View

Note: XXXX is the Quality Code  
YYYY is the date code

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4614D6	-55°C to +150°C	PDFN5×6-8L-B	5000

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

Parameter	Symbol	Limit		Unit
		N	P	
Drain-source voltage	$V_{DS}$	40	-40	V
Gate-source voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Operating junction Temperature range	$T_j$	-55—150	-55—150	°C
Drain Current-Continuous	$I_D$	16	-16	A

(Silicon Limited)	T <sub>A</sub> =70°C		10.5	-12.5	
Pulsed Drain Current (Package Limited)	I <sub>DM</sub>	32	-24	A	
Avalanche Current <sup>C</sup>	I <sub>AS</sub> , I <sub>AR</sub>	16	-20	A	
Avalanche energy L=0.1mH <sup>C</sup>	E <sub>AS</sub> , E <sub>AR</sub>	12	25	mJ	
Power Dissipation <sup>B</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	10	20	W
	T <sub>A</sub> =100°C		4	8	
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>		-55—150		°C

## Thermal Characteristics

Parameter	Symbol	Device	Typ	Max	Unit
Maximum Junction-to-Ambient <sup>A</sup>	R <sub>θJA</sub>	n-ch	30	40	°C/W
Maximum Junction-to-Ambient <sup>A</sup>		n-ch	55	70	
Maximum Junction-to-Lead <sup>B</sup>	R <sub>θJC</sub>	n-ch	9	12	°C/W
Maximum Junction-to-Ambient <sup>A</sup>		p-ch	20	30	
Maximum Junction-to-Ambient <sup>A</sup>	R <sub>θJA</sub>	p-ch	48	65	°C/W
Maximum Junction-to-Lead <sup>B</sup>		p-ch	5	6	

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

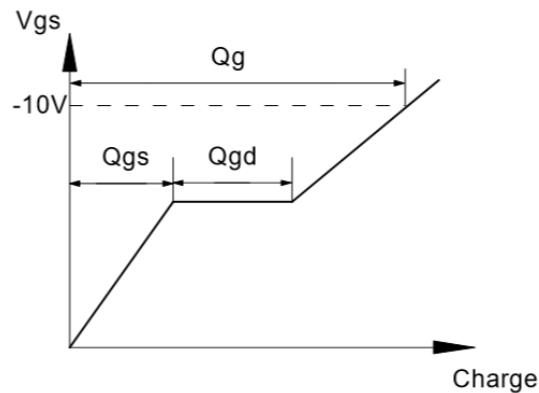
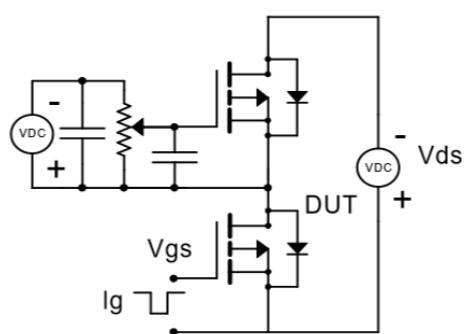
**N-Channel Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	-	-	V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-body leakage	$I_{\text{GSS}}$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm20\text{V}$	-	-	$\pm100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.35	2.0	V
Drain-source on-state resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=16\text{A}$	-	15	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=10\text{A}$	-	17	23	
Forward transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=8\text{A}$	-	15	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{\text{ISS}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$	-	415	-	$\text{pF}$
Output capacitance	$C_{\text{OSS}}$		-	112	-	
Reverse transfer capacitance	$C_{\text{RSS}}$		-	11	-	
Gate resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	1.1	-	$\Omega$
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{\text{D(ON)}}$	$V_{\text{DS}}=20\text{V}$ $V_{\text{GS}}=10\text{V}$ $R_L=1.8\Omega$ $R_{\text{GEN}}=3\Omega$	-	4	-	$\text{ns}$
Rise time	$t_r$		-	3	-	
Turn-off delay time	$t_{\text{D(OFF)}}$		-	15	-	
Fall time	$t_f$		-	2	-	
Total gate charge	$Q_g$	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=8\text{A}$ $V_{\text{GS}}=10\text{V}$	-	6.5	-	$\text{nC}$
Gate-source charge	$Q_{\text{gs}}$		-	1.2	-	
Gate-drain charge	$Q_{\text{gd}}$		-	1.1	-	

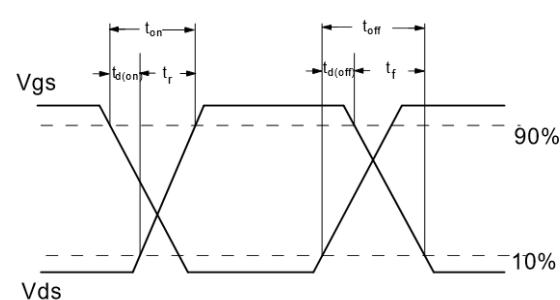
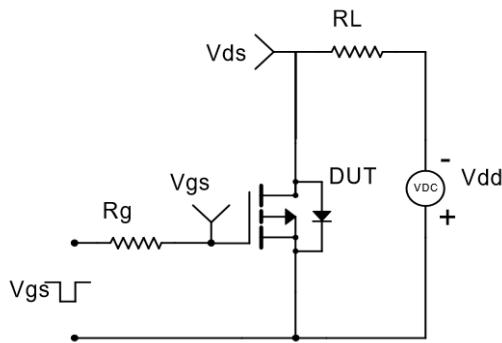
**P-Channel Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40	-	-	V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-body leakage	$I_{\text{GSS}}$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm20\text{V}$	-	-	$\pm100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.35	-2.0	V
Drain-source on-state resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-6\text{A}$	-	29	35	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	-	38.5	46	
Forward transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-6\text{A}$	-	18	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{\text{ISS}}$	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$	-	1040	-	$\text{pF}$
Output capacitance	$C_{\text{OSS}}$		-	180	-	
Reverse transfer capacitance	$C_{\text{RSS}}$		-	125	-	
Gate resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	4	-	$\Omega$
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{\text{D}(\text{ON})}$	$V_{\text{DS}}=-20\text{V}$ $V_{\text{GS}}=-10\text{V}$ $R_L=2.3\Omega$ $R_{\text{GEN}}=3\Omega$	-	10	-	$\text{ns}$
Rise time	$t_r$		-	5.5	-	
Turn-off delay time	$t_{\text{D}(\text{OFF})}$		-	3.6	-	
Fall time	$t_f$		-	4.6	-	
Total gate charge	$Q_g$	$V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-6\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	19	-	$\text{nC}$
Gate-source charge	$Q_{\text{gs}}$		-	3.6	-	
Gate-drain charge	$Q_{\text{gd}}$		-	4.6	-	

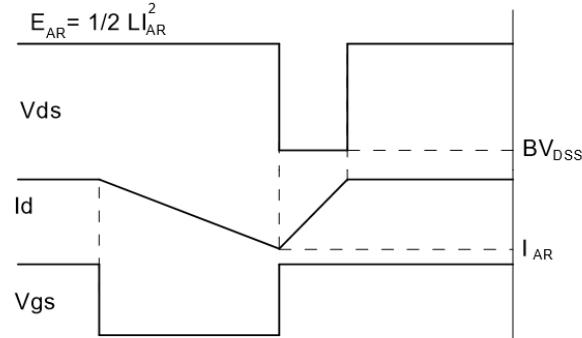
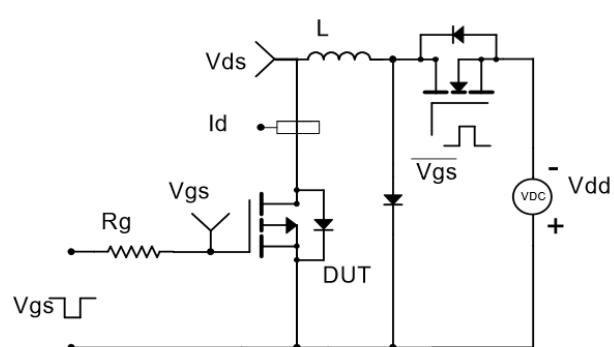
### Gate Charge Test Circuit & Waveform



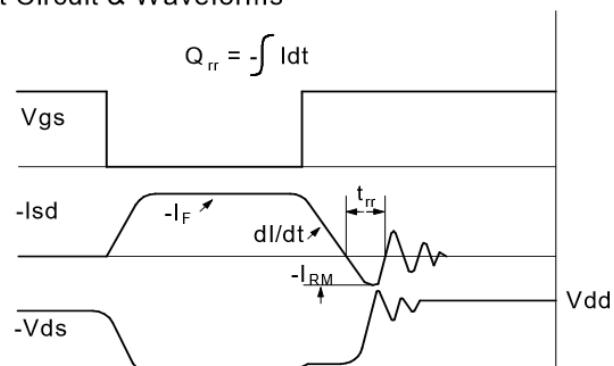
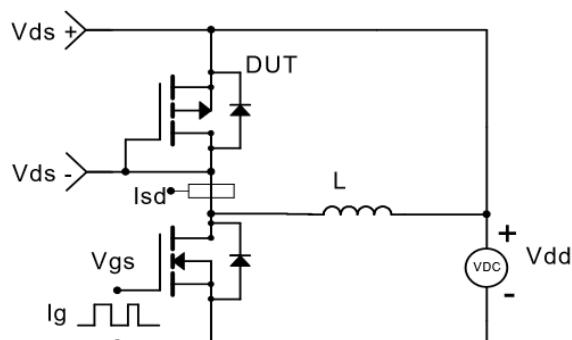
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

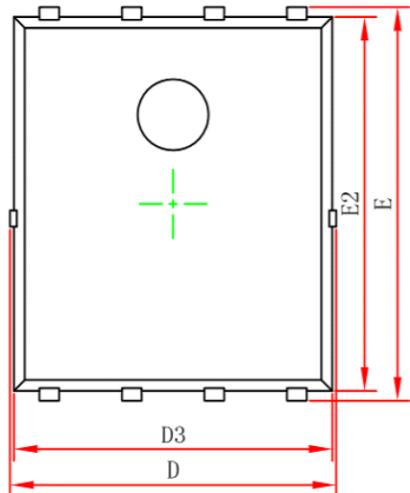


### Diode Recovery Test Circuit & Waveforms

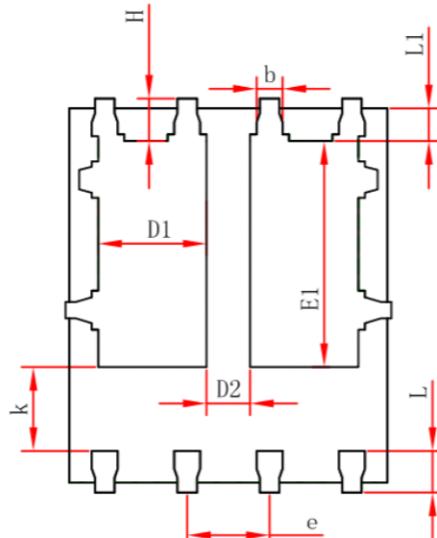


## Package Information

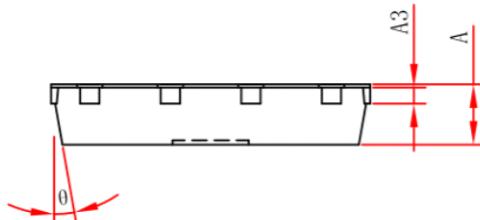
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Top View



Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.154REF.		0.006REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°